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ADVANCE PRODUCT CHANGE NOTIFICATION

APCN: APCN194303

Date: October 25, 2019

Subject: Planned Qualification of the Following Sites for Select Analog and MCU Products

- a. J-Devices Usuki for 300mm DPS Process
- b. J-Devices Kumamoto for BGA Assembly and Test Site

To: TOKYO ELECTRON DEVICE

Description of Change:

Cypress is planning to migrate all the products currently running at J-Devices Kitsuki to alternate J-Devices factories at Usuki ((1913-2, Takegashita, Fukura, Usuki-shi, Oita 875-0053, Japan) and Kumamoto (272-10, Takaono, Ozu-machi, Kikuchi-gun, Kumamoto 869-1232, Japan). This change is driven by the J-Devices' notification to cease manufacturing operations at their Kitsuki factory (2820-2, Minami-Kitsuki, Kitsuki-shi, Oita 873-0002, Japan) by March 2021. This is an advance notification and no immediate action is needed.

Refer to the table below for complete schedule of the activity, PCN issue and ship start dates.

Category	Product type	MPN Change	Estimated Cypress Qualification Date	Estimated PCN/PIN Publication Date	Estimated Implementation Date
DPS Usuki	Auto	NO	Q1 2020	Q1 2020	Q4 2020
	Non-Auto	NO	Q1 2020	Q1 2020	Q2 2020
BGA Kumamoto	Non-Auto	YES	Q1 2020	Q1 2020	Q3 2020
TEST Kumamoto	Auto	NO	Q4 2019	Q1 2020	Q4 2020
	Non-Auto	NO	Q4 2019	Q1 2020	Q3 2020

J-Devices Usuki and Kumamoto are certified by international quality standards, ISO 9001 and IATF19649. J-Devices certificates can be viewed on their corporate web site below:

<https://amkor.com/quality-management/>.

Benefit of Change:

Cypress will have the added capability to meet varying market demand, and to ensure consistent and reliable delivery performance to customers.

Part Numbers Affected: 713

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Affected parts are categorized to three groups:

DPS Usuki: Site change of DPS process.

BGA Kumamoto: Site change of BGA packaging Assembly and Test process

TEST Kumamoto: Site change of Test process only.

Category of JD Kitsuki closure				
Process	Detail process	DPS Usuki	BGA Kumamoto	TEST Kumamoto
Assembly	Back Grinding	X	X	No change (assembly at other facilities)
	Dicing	X	X	
	Die Attach	No change (Usuki/Fukuoka)	X	
	Wire Bonding		X	
	Molding		X	
	Plating		X	
	Trim/Form		X	
	Marking		X	
TEST	TEST		X	X
	B/I		X	X

Qualification Status:

Estimated completion dates for internal qualification of Cypress part numbers and sample availability dates are provided in this notification.

Approximate Implementation Date:

Estimated implementation dates are provided in this notification.

Anticipated Impact:

No impact is expected in datasheet parameters, package composition and package pin-out.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

This is an information only announcement. No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration